

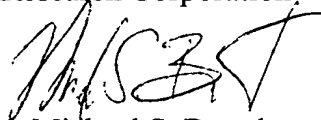
**REMARKS**

Amendments were made to the claims to better define that which the  
5 Applicant regards as the invention. Applicant submits that these amendments are  
supported by the specification and the drawings and do not add new matter.

The Applicant respectfully requests examination on the merits of the subject  
application, and respectfully submit that all of the pending claims are in condition for  
allowance. Accordingly, a notice of allowance is respectfully requested. If the  
10 Examiner has any questions concerning the present amendment, the Examiner is  
kindly requested to contact the undersigned at (510) 572-1667. If any fees are due in  
connection with filing this amendment, the Commissioner is authorized to charge  
Deposit Account 501842 (Order No. P0815). A duplicate copy of the transmittal is  
enclosed for this purpose.  
15 (510) 572-1667.

May 13, 2002

Respectfully submitted,  
Lam Research Corporation.

  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

5 ANTOLIK, Jerrel K.

Application No. 09/916,784

10 Filed: July 27, 2001

For: Twist-N-Lock Wafer Area Pressure  
Ring and Assembly

) Examiner: Unknown  
)  
)  
) Art Unit: 1763  
)  
) Docket No. P0815  
)  
) Date: May 13, 2002  
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)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231 on May 13, 2002.

Signed:

*Sharon D. Tillery*  
Sharon D. Tillery



MARKED UP CLAIMS

25 4. (Amended) The wafer area pressure confinement apparatus according to claim 1, wherein said hanging [orifice] bore is twistingly attached to said interior of said chamber via chamber plungers.

30 5. (Amended) The wafer area pressure confinement apparatus of claim 1, wherein said hanging bore mates with a twist and lock adapter by aligning said adapter with said hanging bore, and;

moving said pressure confinement apparatus vertical to said adapter such that  
35 said adapter fits in [said] a forward portion of said hanging [orifice] bore and whereby a 5 degree twist of said wafer area pressure confinement apparatus attaches said adapter to [the] a rearward portion of said hanging [orifice] bore.

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8. (Amended) A method of attaching for attaching at least one wafer area pressure ring to the interior of a plasma processing chamber comprising:

providing a hanging adapter to be hung from the chamber ceiling;

aligning said hanging adapter [aligning said adapter] with a hanging bore

5 contained on at least one wafer area pressure ring, and;

moving [said pressure confinement apparatus] said at least one wafer area pressure ring vertical to said adapter such that said adapter fits in [said] a forward portion of said hanging [orifice] bore and whereby a 5 degree twist of [said wafer area pressure confinement apparatus] said at least one wafer area pressure ring attaches

10 said adapter to [the] a rearward portion of said hanging [orifice] bore.